Reply to Office Action dated April 13, 2007

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- (Currently Amended) A substrate bonding apparatus for manufacturing a 1. liquid crystal display (LCD) device, comprising:
 - a base frame;
 - a lower chamber unit mounted to the base frame;
 - an upper chamber unit joinable to the lower chamber unit;
 - an upper stage fixed to the upper chamber unit for securing a first substrate;
 - a lower stage fixed to the lower chamber unit for securing a second substrate;
- [[a]] at least one first plurality of elastic members member arranged between the upper stage and the upper chamber unit; and
- [[a]] at least one second plurality of elastic members member arranged between the lower stage and the lower chamber unit,

wherein at least one of the upper and lower stages includes: a fixing plate coupled to a corresponding one of the upper and lower chamber units; and a securing plate for securing a corresponding one of the first and second substrates, and wherein at least one of the first and second elastic members is arranged between the fixing plate and the securing plate.

(Currently Amended) The substrate bonding apparatus according to claim 1, 2. wherein the upper and lower chamber units are convexly bendable within the substrate bonding apparatus; and

the plurality of first and second elastic members exert restoration forces to the upper and lower chamber units.

(Currently Amended) The substrate bonding apparatus according to claim 1, 3. wherein the plurality of first and second elastic members include a coil spring.

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4. (Currently Amended) The substrate bonding apparatus according to claim 1, wherein the plurality of first and second elastic members include an initially-coned disk spring.

5. (Currently Amended) The substrate bonding apparatus according to claim 1, wherein the plurality of first and second elastic members include a plate spring.

Claims 6-13 (Canceled)

- 14. (Currently Amended) The substrate bonding apparatus according to claim [[8]] 1, wherein the securing plate includes a plurality of electrostatic chucks.
- 15. (Currently Amended) The substrate bonding apparatus according to claim 14, wherein the <u>plurality of first and second</u> elastic members are arranged in correspondence with positions of the plurality of electrostatic chucks.
- 16. (Currently Amended) The substrate bonding apparatus according to claim [[8]] 1, wherein the securing plate includes stainless steel.
- 17. (Currently Amended) The substrate bonding apparatus according to claim [[8]] 1, wherein the securing plate includes an aluminum alloy.
- 18. (Currently Amended) The substrate bonding apparatus according to claim [[8]] 1, wherein the securing plate is at least about 40mm thick.
 - 19. (Canceled)
 - 20. (Canceled)
- 21. (Withdrawn) A method of fabricating a display, comprising:

 providing an upper stage coupled to an upper chamber unit via at least one elastic member;

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providing a lower stage coupled to a lower chamber unit via at least one elastic member;

loading a first substrate onto the upper stage;

loading a second substrate onto the lower stage;

joining the upper and lower chamber units to create an interior space surrounding the first and second substrates;

evacuating the interior space, wherein an interior surface of the upper and lower chamber units is convexly bendable with respect to the first and second substrates while a surface of the upper stage opposing a surface of the lower stage remains substantially parallel to the surface of the lower stage; and

bonding the first and second substrates together within the interior space.

- 22. (Withdrawn) The method of fabricating a display according to claim 21, wherein the bonding includes bonding the first and second substrates in the evacuated interior space.
- 23. (New) A substrate bonding apparatus for manufacturing a liquid crystal display (LCD) device, comprising:
 - a base frame;
 - a lower chamber unit mounted to the base frame;
 - an upper chamber unit joinable to the lower chamber unit;
 - an upper stage fixed to the upper chamber unit for securing a first substrate;
 - a lower stage fixed to the lower chamber unit for securing a second substrate;
- at least one first elastic member arranged between the upper stage and the upper chamber unit; and

at least one second elastic member arranged between the lower stage and the lower chamber unit,

wherein at least one of the upper and lower stages includes: a fixing plate coupled to a corresponding one of the upper and lower chamber units; and a securing plate for securing a corresponding one of the first and second substrates, and wherein at least one of the first and second elastic members is arranged between the fixing plate and the securing plate and wherein Application No.: 10/625,525 Reply to Office Action dated April 13, 2007

the securing plate includes a plurality of holes for transmitting a suction force to secure a substrate.

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